

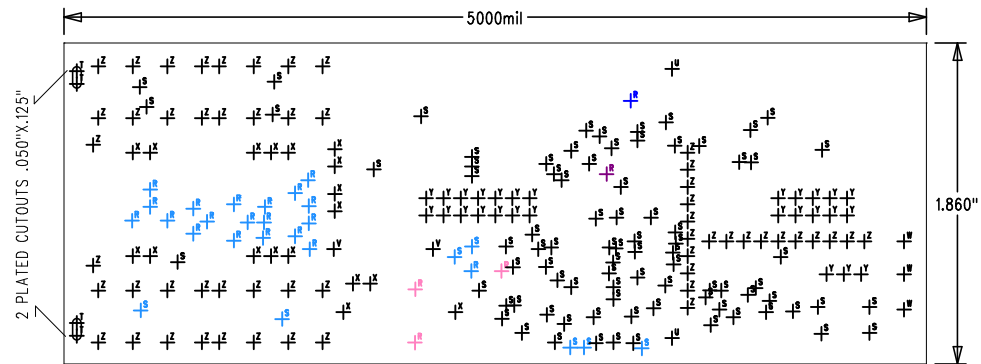
NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL PLATED HOLES TO HAVE MIN. WALL THICKNESS OF .0015" COPPER.  
ALL HOLE DIAMETERS ARE AFTER PLATING.  
.005" MIN. ANNULAR RING PERMISSIBLE.
  2. FINISH: SOLDERMASK OVER BARE COPPER. HASL. TIN/LEAD.
  3. SOLDERMASK TO BE PHOTO-IMAGEABLE OR DRY FILM.
  4. SILKSCREEN TO BE NON-CONDUCTIVE EPOXY INK.
  5. BOARD WARPAGE SHALL NOT EXCEED .010" PER DIAGONAL INCH OF BOARD.
  6. PCB TO BE FABRICATED PER IPC-A-600 OR MOST CURRENT VERSION.
  7. UNLESS OTHERWISE NOTED, ALL DIMENSIONS ARE IN INCHES.
- TOLERANCE: +/- .003.

SIZE	QTY	SYM	PLTD
22	25	R	PLTD
16	91	S	PLTD
50	4	T	PLTD
98	2	U	PLTD
47	2	V	PLTD
42	3	W	PLTD
45	18	X	PLTD
40	27	Y	PLTD
37	54	Z	PLTD
50 x 125	2	T	PLTD

LAYERS	4
MIN LINE WIDTH/SPACING	12 MIL / 12 MIL
SOLDER MASK	LPI (GREEN) BOTH SIDES
SILK SCREEN	WHITE BOTH SIDES
THICKNESS	0.062"
MATERIAL	FR-4
COPPER THICKNESS	1 OZ.

FABRICATION DESCRIPTION



**NEXLOGIC**  
TECHNOLOGIES  
PRINTED CIRCUIT SOLUTIONS  
(408)436-8150 <http://www.nexlogic.com>  
Date : 10/20/04 JOB # 13254  
Company Name : MBARI  
P/N RF MODEM INTERFACE\_5" REV B

COMPONENT SIDE LAYER 1

DRILL DRAWING